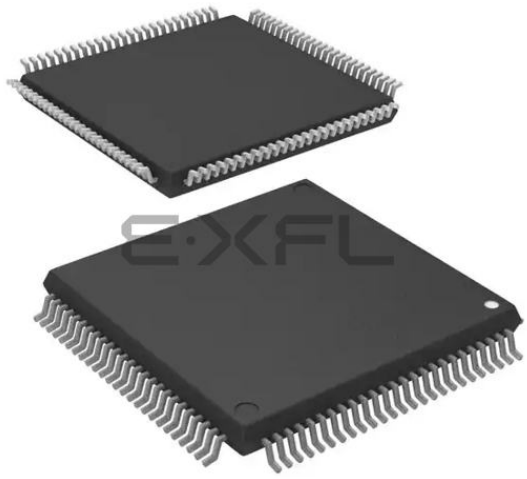

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Applications of "Embedded - Microcontrollers"

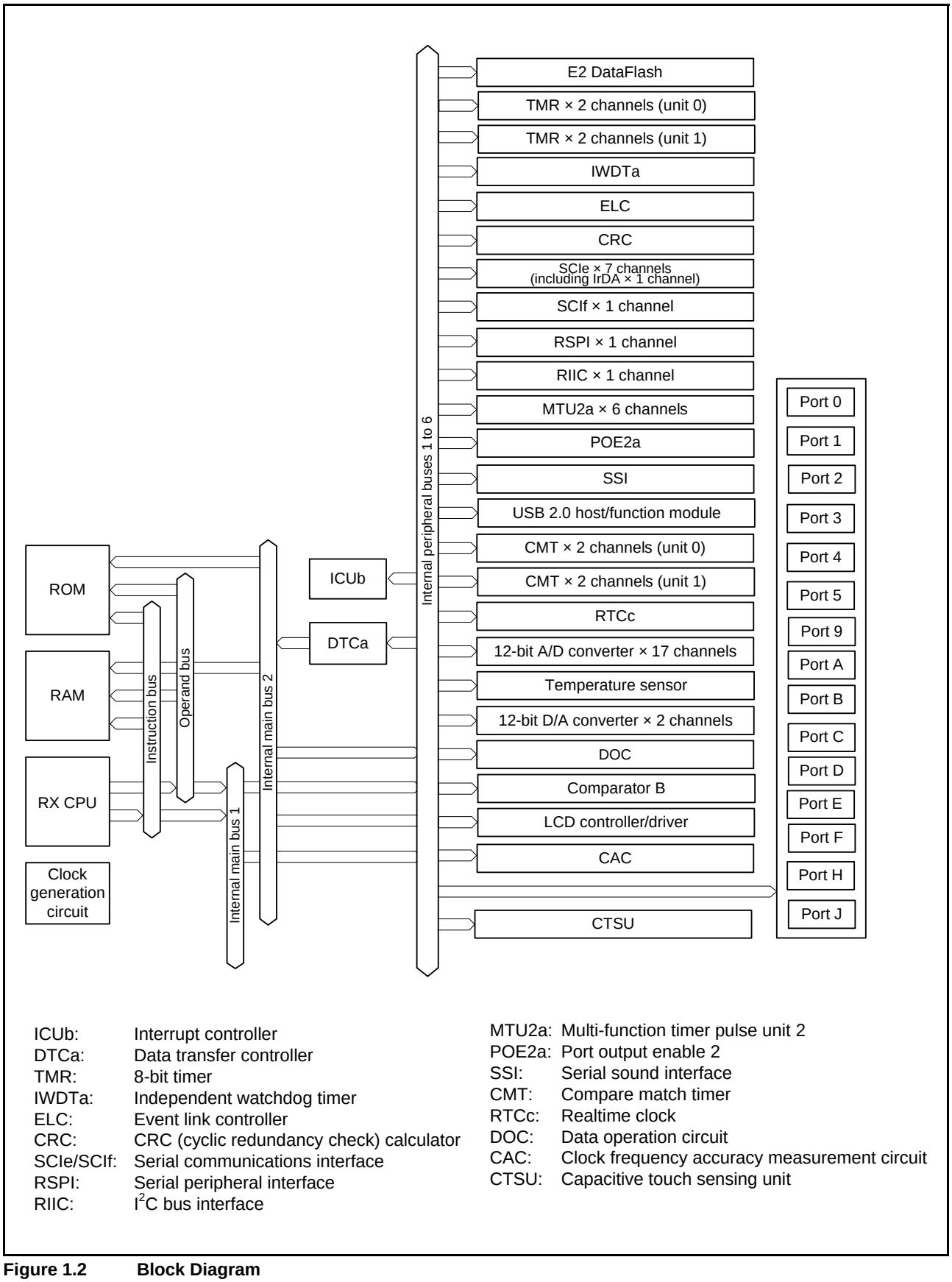
Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SCI, SPI, SSI, USB OTG
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	80
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51138adfp-30

Table 1.1 Outline of Specifications (2/3)

Classification	Module/Function	Description
DMA	Data transfer controller (DTCa)	• Transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Interrupts • Chain transfer function
I/O ports	General I/O ports	100-pin /64-pin • I/O: 82/46 • Input: 2/2 • Pull-up resistors: 69/38 • Open-drain outputs: 61/34 • 5-V tolerance: 4/4
Event link controller (ELC)		• Event signals of 44 types can be directly connected to the module • Operations of timer modules are selectable at event input • Capable of event link operation for port B
Multi-function pin controller (MPC)		Capable of selecting the input/output function from multiple pins
Timers	Multi-function timer pulse unit 2 (MTU2a)	• (16 bits × 6 channels) × 1 unit • Time bases for the six 16-bit timer channels can be provided via up to 16 pulse-input/output lines and three pulse-input lines • Select from among eight or seven counter-input clock signals for each channel (PCLK/1, PCLK/4, PCLK/16, PCLK/64, PCLK/256, PCLK/1024, MTCLKA, MTCLKB, MTCLKC, MTCLKD) other than channel 5, for which only four signals are available. • Input capture function • 21 output compare/input capture registers • Pulse output mode • Complementary PWM output mode • Reset synchronous PWM mode • Phase-counting mode • Capable of generating conversion start triggers for the A/D converter
	Port output enable 2 (POE2a)	Controls the high-impedance state of the MTU's waveform output pins
	Compare match timer (CMT)	• (16 bits × 2 channels) × 2 units • Select from among four clock signals (PCLK/8, PCLK/32, PCLK/128, PCLK/512)
	Independent watchdog timer (IWDTa)	• 14 bits × 1 channel • Count clock: Dedicated low-speed on-chip oscillator for the IWDT Frequency divided by 1, 16, 32, 64, 128, or 256
	Realtime clock (RTCA)	• Clock source: Sub-clock • Calendar count mode or binary count mode selectable • Interrupts: Alarm interrupt, periodic interrupt, and carry interrupt
	Low power timer (LPT)	• 16 bits × 1 channel • Clock source: Sub-clock, Dedicated low-speed on-chip oscillator for the IWDT Frequency divided by 2, 4, 8, 16, or 32
	8-bit timer (TMR)	• (8 bits × 2 channels) × 2 units • Seven internal clocks (PCLK/1, PCLK/2, PCLK/8, PCLK/32, PCLK/64, PCLK/1024, and PCLK/8192) and an external clock can be selected • Pulse output and PWM output with any duty cycle are available • Two channels can be cascaded and used as a 16-bit timer
Communication functions	Serial communications interfaces (SCIe, SCIf)	• 8 channels (channel 0, 1, 2, 5, 6, 8, and 9: SCIe, channel 12: SCIf) • Serial communications modes: Asynchronous, clock synchronous, and smart card interface • On-chip baud rate generator allows selection of the desired bit rate • Choice of LSB-first or MSB-first transfer • Average transfer rate clock can be input from MTU2 timers • Simple I^2C • Simple SPI • Master/slave mode supported (SCIf only) • Start frame and information frame are included (SCIf only) • Start-bit detection in asynchronous mode: Low level or falling edge is selectable
	IrDA interface (IRDA)	• 1 channel (SCI5 used) • Supports encoding/decoding of waveforms conforming to IrDA standard 1.0
	I^2C bus interface (RIIC)	• 1 channel • Communications formats: I^2C bus format/SMBus format • Master mode or slave mode selectable • Supports fast mode

1.3 Block Diagram

Figure 1.2 shows a block diagram.



ICUb: Interrupt controller
DTCa: Data transfer controller
TMR: 8-bit timer
IWDTa: Independent watchdog timer
ELC: Event link controller
CRC: CRC (cyclic redundancy check) calculator
SCIe/SCIf: Serial communications interface
RSPI: Serial peripheral interface
RIIC: I^2C bus interface

MTU2a: Multi-function timer pulse unit 2
POE2a: Port output enable 2
SSI: Serial sound interface
CMT: Compare match timer
RTCc: Realtime clock
DOC: Data operation circuit
CAC: Clock frequency accuracy measurement circuit
CTSU: Capacitive touch sensing unit

Figure 1.2 Block Diagram

Table 1.5 List of Pins and Pin Functions (100-Pin LFQFP) (2/3)

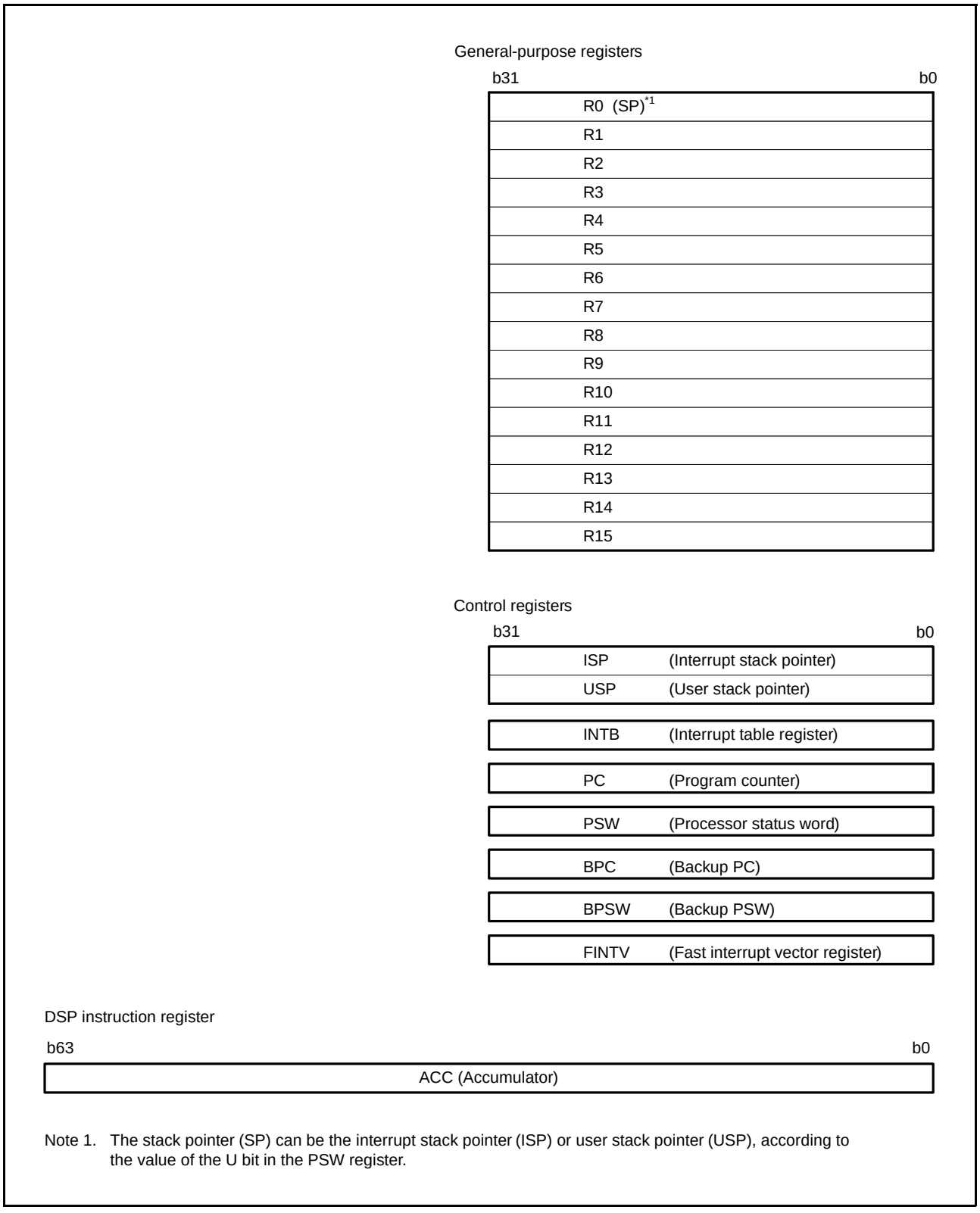
Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC, TMR)	Communication (SCIe, SCIf, RSPI, RIIC, USB, SSI)	LCD, Touch	Others
36		P11	MTIC5U/POE0#	RXD12/RXDX12/SMISO12/ SSCL12/ RXD0/SMISO0/SSCL0	SEG02	IRQ7
37		P10	MTIC5V/POE1#	TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12/TXD0/SMOSI0/SSDA0	SEG03	IRQ6
38		P56	MTIOC1A/MTIC5W/ POE2#	TXD1/SMOSI1/SSDA1	SEG04	IRQ5
39		P53	MTIOC2B	SSLA0/CTS2#/RTS2#/SS2#	SEG05	
40		P52		MISOA/RXD2/SMISO2/SSCL2	SEG06	
41		P51	MTIOC4C	RSPCKA/SCK2	SEG07	
42		P50	MTIOC2A	MOSIA/TXD2/SMOSI2/SSDA2	SEG08	
43		P55	MTIOC4D/TMO3		VL1	
44		P54	MTIOC4B/TMCI1		VL2	
45		PC7	MTIOC3A/MTCLKB/ TMO2	TXD1/SMOSI1/SSDA1/MISOA/ TXD8/SMOSI8/SSDA8/ USB0_OVRCURB	VL3	CACREF
46		PC6	MTIOC3C/MTCLKA/ TMCI2	RXD1/SMISO1/SSCL1/MOSIA/ RXD8/SMISO8/SSCL8/ USB0_EXICEN	VL4	
47		PC5	MTIOC3B/MTCLKD/ TMRI2	SCK1/RSPCKA/SCK8/USB0_ID	COM0	
48		PC4	MTIOC3D/MTCLKC/ POE0#/TMCI1	SSLA0/CTS8#/RTS8#/SS8#/SCK5/ USB0_VBUSEN/USB0_VBUS *1	COM1	IRQ2/CLKOUT
49		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5/IRTXD5	COM2	
50		PC2	MTIOC4B	RXD5/SMOSI5/SSCL5/IRRXD5/ SSLA3	COM3	
51		PC1	MTIOC3A	SCK5/SSLA2	SEG09	
52		PC0	MTIOC3C	CTS5#/RTS5#/SS5#/SSLA1	SEG10	
53		PB7	MTIOC3B	TXD9/SMOSI9/SSDA9/SSITXD0	SEG11/ COM4	
54		PB6	MTIOC3D	RXD9/SMISO9/SSCL9/SSIRXD0	SEG12/ COM5	
55		PB5	MTIOC1B/MTIOC2A/ POE1#/TMRI1	SCK9/SSISCK0	SEG13/ COM6	
56		PB4		CTS9#/RTS9#/SS9#	SEG14	
57		PB3	MTIOC0A/MTIOC3B/ MTIOC4A/POE3#/TMO0	SCK6/AUDIO_MCLK/ USB0_OVRCURA	SEG15/ COM7	
58		PB2		CTS6#/RTS6#/SS6#	SEG16	
59		PB1	MTIOC0C/MTIOC4C/ TMCI0	TXD6/SMOSI6/SSDA6/SSIWS0	SEG17	IRQ4
60	VCC					
61		PB0	MTIOC0C/MTIC5W/ RTCOUT	SCL0/RSPCKA/RXD6/SMISO6/ SSCL6		IRQ2/ADTRG0#
62	VSS					
63		PA6	MTIC5V/MTCLKB/ MTIOC2A/POE2#/TMCI3	CTS5#/RTS5#/SS5#/SDA0/MOSIA/ RXD8/SMISO8/SSCL8		IRQ3
64		PA7		TXD8/SMOSI8/SSDA8	SEG18	
65		PA5		SCK8	SEG19	
66		PA4	MTIOC2B/MTIC5U/ MTCLKA/TMRI0	TXD5/SMOSI5/SSDA5/IRTXD5/ SSLA0/CTS8#/RTS8#/SS8#	SEG20	IRQ5/CVREFB1
67		PA3	MTIOC0D/MTIOC1B/ MTCLKD/POE0#	RXD5/SMISO5/SSCL5/IRRXD5/ MISOA	SEG21	IRQ6/CMPB1

Table 1.6 List of Pins and Pin Functions (100-Pin TFLGA) (1/3)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC, TMR)	Communication (SCIe, SCIf, RSPI, RIIC, USB, SSI)	LCD, Touch	Others
A1		P02	MTIOC0D/POE3#/TMRI3	RXD6/SMISO6/SSCL6	TS2	
A2		P07		TXD6/SMOSI6/SSDA6	TS0	ADTRG0#
A3	AVCC0					
A4	AVSS0					
A5		P44*2				AN004
A6		P92*2				AN021
A7		PD3	POE8#		SEG36	IRQ3
A8		PE6			SEG34	IRQ6/AN014
A9		PE7			SEG33	IRQ7/AN015/ CMPOB0
A10		PE0	MTIOC2A/POE3#	SCK12/CTS9#/RTS9#/SS9#/ SSISCK0	SEG32	IRQ0/AN008
B1		P25	MTIOC4C/MTCLKB		TS4	ADTRG0#
B2		P04	MTIOC0A/POE2#/TMCI3	SCK6	TS1	
B3		PJ2				DA1
B4	VREFL0	PJ7*2				
B5		P90*2				AN005
B6		PD0			SEG39	IRQ0
B7		PD4	POE3#		SEG35	IRQ4
B8		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/ SSCL12/SSIRXD0	SEG30	IRQ7/AN010/ CVREFB0
B9		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12/SSITXD0	SEG31	IRQ1/AN009/ CMPB0
B10		PE3	MTIOC0A/MTIOC1B/ MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/RSPCKA/ SCK9/AUDIO_MCLK	SEG29	IRQ3/AN011
C1		PJ3	MTIOC3C	CTS6#/RTS6#/SS6#	TS3	
C2		P24	MTIOC4A/MTCLKA/ TMRI1		TS5	
C3	VREFH0	PJ6*2				
C4	VREFH	P41*2				AN001
C5	VREFL	P42*2				AN002
C6		P91*2				AN007
C7		PD1	MTIOC4B		SEG38	IRQ1
C8		PD2	MTIOC4D		SEG37	IRQ2
C9		PE5	MTIOC2B/MTIOC4C	MISOA/TXD9/SMOSI9/SSDA9	SEG27	IRQ5/AN013/ CMPOB1
C10		PE4	MTIOC1A/MTIOC3A/ MTIOC4D	MOSIA/RXD9/SMISO9/SSCL9/ SSIWS0	SEG28	IRQ4/AN012
D1		P22	MTIOC3B/MTCLKC/ TMO0	SCK0	TS7	
D2		P23	MTIOC3D/MTCLKD	CTS0#/RTS0#/SS0#	TS6	
D3		P21	MTIOC1B/TMCI0	RXD0/SMISO0/SSCL0	TS8	
D4		PJ0				DA0
D5		P43*2				AN003
D6		P46*2				AN006
D7		PF6	MTIOC3C		SEG26	
D8		PF7	MTIOC3A		SEG25	

2. CPU

Figure 2.1 shows the register set of the CPU.



Note 1. The stack pointer (SP) can be the interrupt stack pointer (ISP) or user stack pointer (USP), according to the value of the U bit in the PSW register.

Figure 2.1 Register Set of the CPU

Table 4.1 List of I/O Registers (Address Order) (8/23)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 800Ch	CMT1	Compare Match Timer Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8010h	CMT	Compare Match Timer Start Register1	CMSTR1	16	16	2 or 3 PCLKB
0008 8012h	CMT2	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 8014h	CMT2	Compare Match Counter	CMCNT	16	16	2 or 3 PCLKB
0008 8016h	CMT2	Compare Match Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8018h	CMT3	Compare Match Timer Control Register	CMCR	16	16	2 or 3 PCLKB
0008 801Ah	CMT3	Compare Match Counter	CMCNT	16	16	2 or 3 PCLKB
0008 801Ch	CMT3	Compare Match Constant Register	CMCOR	16	16	2 or 3 PCLKB
0008 8030h	IWDT	IWDT Refresh Register	IWDTRR	8	8	2 or 3 PCLKB
0008 8032h	IWDT	IWDT Control Register	IWDTCR	16	16	2 or 3 PCLKB
0008 8034h	IWDT	IWDT Status Register	IWDTSR	16	16	2 or 3 PCLKB
0008 8036h	IWDT	IWDT Reset Control Register	IWDTRCR	8	8	2 or 3 PCLKB
0008 8038h	IWDT	IWDT Count Stop Control Register	IWDTCSTPR	8	8	2 or 3 PCLKB
0008 8040h	R12DA	D/A Data Register 0	DADR0	16	16	2 or 3 PCLKB
0008 8042h	R12DA	D/A Data Register 1	DADR1	16	16	2 or 3 PCLKB
0008 8044h	R12DA	D/A Control Register	DACR	8	8	2 or 3 PCLKB
0008 8045h	R12DA	DADRm Format Select Register	DADPR	8	8	2 or 3 PCLKB
0008 8046h	R12DA	D/A A/D Synchronous Start Control Register	DAADSCR	8	8	2 or 3 PCLKB
0008 8047h	R12DA	D/A VREF Control Register	DAVREFCR	8	8	2 or 3 PCLKB
0008 8200h	TMR0	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8201h	TMR1	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8202h	TMR0	Timer Control/Status Register	TCSR	8	8	2 or 3 PCLKB
0008 8203h	TMR1	Timer Control/Status Register	TCSR	8	8	2 or 3 PCLKB
0008 8204h	TMR0	Time Constant Register A	TCORA	8	8	2 or 3 PCLKB
0008 8205h	TMR1	Time Constant Register A	TCORA	8	8*1	2 or 3 PCLKB
0008 8206h	TMR0	Time Constant Register B	TCORB	8	8	2 or 3 PCLKB
0008 8207h	TMR1	Time Constant Register B	TCORB	8	8*1	2 or 3 PCLKB
0008 8208h	TMR0	Timer Counter	TCNT	8	8	2 or 3 PCLKB
0008 8209h	TMR1	Timer Counter	TCNT	8	8*1	2 or 3 PCLKB
0008 820Ah	TMR0	Timer Counter Control Register	TCCR	8	8	2 or 3 PCLKB
0008 820Bh	TMR1	Timer Counter Control Register	TCCR	8	8*1	2 or 3 PCLKB
0008 820Ch	TMR0	Time Count Start Register	TCSTR	8	8	2 or 3 PCLKB
0008 8210h	TMR2	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8211h	TMR3	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8212h	TMR2	Timer Control/Status Register	TCSR	8	8	2 or 3 PCLKB
0008 8213h	TMR3	Timer Control/Status Register	TCSR	8	8	2 or 3 PCLKB
0008 8214h	TMR2	Time Constant Register A	TCORA	8	8	2 or 3 PCLKB
0008 8215h	TMR3	Time Constant Register A	TCORA	8	8*1	2 or 3 PCLKB
0008 8216h	TMR2	Time Constant Register B	TCORB	8	8	2 or 3 PCLKB
0008 8217h	TMR3	Time Constant Register B	TCORB	8	8*1	2 or 3 PCLKB
0008 8218h	TMR2	Timer Counter	TCNT	8	8	2 or 3 PCLKB
0008 8219h	TMR3	Timer Counter	TCNT	8	8*1	2 or 3 PCLKB
0008 821Ah	TMR2	Timer Control Register	TCCR	8	8	2 or 3 PCLKB
0008 821Bh	TMR3	Timer Control Register	TCCR	8	8*1	2 or 3 PCLKB
0008 821Ch	TMR2	Time Count Start Register	TCSTR	8	8	2 or 3 PCLKB
0008 8280h	CRC	CRC Control Register	CRCCR	8	8	2 or 3 PCLKB
0008 8281h	CRC	CRC Data Input Register	CRCDIR	8	8	2 or 3 PCLKB
0008 8282h	CRC	CRC Data Output Register	CRCDOR	16	16	2 or 3 PCLKB
0008 8300h	RIIC0	I^2C Bus Control Register 1	ICCR1	8	8	2 or 3 PCLKB
0008 8301h	RIIC0	I^2C Bus Control Register 2	ICCR2	8	8	2 or 3 PCLKB
0008 8302h	RIIC0	I^2C Bus Mode Register 1	ICMR1	8	8	2 or 3 PCLKB
0008 8303h	RIIC0	I^2C Bus Mode Register 2	ICMR2	8	8	2 or 3 PCLKB

Table 4.1 List of I/O Registers (Address Order) (10/23)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 860Eh	MTU	Timer Output Control Register 1	TOCR1	8	8	2 or 3 PCLKB
0008 860Fh	MTU	Timer Output Control Register 2	TOCR2	8	8	2 or 3 PCLKB
0008 8610h	MTU3	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8612h	MTU4	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8614h	MTU	Timer Cycle Data Register	TCDR	16	16	2 or 3 PCLKB
0008 8616h	MTU	Timer Dead Time Data Register	TDDR	16	16	2 or 3 PCLKB
0008 8618h	MTU3	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 861Ah	MTU3	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 861Ch	MTU4	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 861Eh	MTU4	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 8620h	MTU	Timer Subcounter	TCNTS	16	16	2 or 3 PCLKB
0008 8622h	MTU	Timer Cycle Buffer Register	TCBR	16	16	2 or 3 PCLKB
0008 8624h	MTU3	Timer General Register C	TGRC	16	16	2 or 3 PCLKB
0008 8626h	MTU3	Timer General Register D	TGRD	16	16	2 or 3 PCLKB
0008 8628h	MTU4	Timer General Register C	TGRC	16	16	2 or 3 PCLKB
0008 862Ah	MTU4	Timer General Register D	TGRD	16	16	2 or 3 PCLKB
0008 862Ch	MTU3	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 862Dh	MTU4	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8630h	MTU	Timer Interrupt Skipping Set Register	TITCR	8	8	2 or 3 PCLKB
0008 8631h	MTU	Timer Interrupt Skipping Counter	TITCNT	8	8	2 or 3 PCLKB
0008 8632h	MTU	Timer Buffer Transfer Set Register	TBTER	8	8	2 or 3 PCLKB
0008 8634h	MTU	Timer Dead Time Enable Register	TDER	8	8	2 or 3 PCLKB
0008 8636h	MTU	Timer Output Level Buffer Register	TOLBR	8	8	2 or 3 PCLKB
0008 8638h	MTU3	Timer Buffer Operation Transfer Mode Register	TBTM	8	8	2 or 3 PCLKB
0008 8639h	MTU4	Timer Buffer Operation Transfer Mode Register	TBTM	8	8	2 or 3 PCLKB
0008 8640h	MTU4	Timer A/D Converter Start Request Control Register	TADCR	16	16	2 or 3 PCLKB
0008 8644h	MTU4	Timer A/D Converter Start Request Cycle Set Register A	TADCORA	16	16	2 or 3 PCLKB
0008 8646h	MTU4	Timer A/D Converter Start Request Cycle Set Register B	TADCORB	16	16	2 or 3 PCLKB
0008 8648h	MTU4	Timer A/D Converter Start Request Cycle Set Buffer Register A	TADCOBRA	16	16	2 or 3 PCLKB
0008 864Ah	MTU4	Timer A/D Converter Start Request Cycle Set Buffer Register B	TADCOBRB	16	16	2 or 3 PCLKB
0008 8660h	MTU	Timer Waveform Control Register	TWCR	8	8, 16	2 or 3 PCLKB
0008 8680h	MTU	Timer Start Register	TSTR	8	8, 16	2 or 3 PCLKB
0008 8681h	MTU	Timer Synchronous Register	TSYR	8	8, 16	2 or 3 PCLKB
0008 8684h	MTU	Timer Read/Write Enable Register	TRWER	8	8, 16	2 or 3 PCLKB
0008 8690h	MTU0	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8691h	MTU1	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8692h	MTU2	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8693h	MTU3	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8694h	MTU4	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8695h	MTU5	Noise Filter Control Register	NFCR	8	8, 16	2 or 3 PCLKB
0008 8700h	MTU0	Timer Control Register	TCR	8	8	2 or 3 PCLKB
0008 8701h	MTU0	Timer Mode Register	TMDR	8	8	2 or 3 PCLKB
0008 8702h	MTU0	Timer I/O Control Register H	TIORH	8	8	2 or 3 PCLKB
0008 8703h	MTU0	Timer I/O Control Register L	TIORL	8	8	2 or 3 PCLKB
0008 8704h	MTU0	Timer Interrupt Enable Register	TIER	8	8	2 or 3 PCLKB
0008 8705h	MTU0	Timer Status Register	TSR	8	8	2 or 3 PCLKB
0008 8706h	MTU0	Timer Counter	TCNT	16	16	2 or 3 PCLKB
0008 8708h	MTU0	Timer General Register A	TGRA	16	16	2 or 3 PCLKB
0008 870Ah	MTU0	Timer General Register B	TGRB	16	16	2 or 3 PCLKB
0008 870Ch	MTU0	Timer General Register C	TGRC	16	16	2 or 3 PCLKB
0008 870Eh	MTU0	Timer General Register D	TGRD	16	16	2 or 3 PCLKB
0008 8720h	MTU0	Timer General Register E	TGRE	16	16	2 or 3 PCLKB

Table 5.7 DC Characteristics (5) (1/2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32 MHz	I_{CC}	3.6	—	mA	
				ICLK = 16 MHz		2.4	—		
				ICLK = 8 MHz		1.8	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		14.0	—		
				ICLK = 16 MHz		7.9	—		
				ICLK = 8 MHz		4.9	—		
			All peripheral operation: Max.*3	ICLK = 32 MHz		—	30.0		
		Sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.9	—		
				ICLK = 16 MHz		1.5	—		
				ICLK = 8 MHz		1.3	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		8.2	—		
				ICLK = 16 MHz		4.8	—		
				ICLK = 8 MHz		3.1	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32 MHz		1.1	—		
				ICLK = 16 MHz		0.95	—		
				ICLK = 8 MHz		0.86	—		
			All peripheral operation: Normal*3	ICLK = 32 MHz		6.4	—		
				ICLK = 16 MHz		3.8	—		
				ICLK = 8 MHz		2.4	—		
		Increase during flash rewrite*5				2.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*6	ICLK = 12 MHz	I_{CC}	2.1	—	mA	
				ICLK = 8 MHz		1.4	—		
				ICLK = 1 MHz		0.77	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		6.3	—		
				ICLK = 8 MHz		4.6	—		
				ICLK = 1 MHz		1.6	—		
			All peripheral operation: Max.*7	ICLK = 12 MHz		—	14.2		
		Sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.4	—		
				ICLK = 8 MHz		0.90	—		
				ICLK = 1 MHz		0.68	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		3.9	—		
				ICLK = 8 MHz		2.9	—		
				ICLK = 1 MHz		1.4	—		
		Deep sleep mode	No peripheral operation*6	ICLK = 12 MHz		1.1	—		
				ICLK = 8 MHz		0.63	—		
				ICLK = 1 MHz		0.55	—		
			All peripheral operation: Normal*7	ICLK = 12 MHz		3.3	—		
				ICLK = 8 MHz		2.4	—		
				ICLK = 1 MHz		1.2	—		
		Increase during flash rewrite*5				2.5	—		

Table 5.10 DC Characteristics (8) (2/2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.*7	Max.	Unit	Test Conditions
USB operating current*3	During USB communication operation under the following settings and conditions • Host controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect peripheral devices via a 1-meter USB cable from the USB port.	I_{USBH}*1	—	4.3 (VCC) 0.9 (VCC_USB)*3	—	mA	
	During USB communication operation under the following settings and conditions • Function controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect the host device via a 1-meter USB cable from the USB port.	I_{USBF}*1	—	3.6 (VCC) 1.1 (VCC_USB)*3	—	mA	
	During suspended state under the following setting and conditions • Function controller operation is set to full-speed mode (pull up the USB0_DP pin) • Software standby mode • Connect the host device via a 1-meter USB cable from the USB port.	I_{SUSP}*2	—	0.35 (VCC) 170 (VCC_USB)*3	—	µA	
CTSU operating current	During measurement (CPU is in sleep mode) Base clock: 2 MHz Pin capacity: 50 pF	I_{CTSU}	—	150	—	µA	

Note 1. Current consumed only by the USB module.
Note 2. Includes the current supplied from the pull-up resistor of the USB0_DP pin to the pull-down resistor of the host device, in addition to the current consumed by this MCU during the suspended state.
Note 3. Current consumed by the power supplies (VCC and VCC_USB).
Note 4. Current consumed only by the comparator B module.
Note 5. Current consumed only by the LCD module. Current when the LCD panel is not connected.
Note 6. Current consumed by the power supply (VCC).
Note 7. When VCC = AVCC0 = VCC_USB = 3.3 V.
Note 8. It does not include the current that flows through external divider resistors.

Table 5.11 DC Characteristics (9)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

Table 5.12 DC Characteristics (10)

Conditions: 0 V ≤ VCC = VCC_USB ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Power-on VCC rising gradient	At normal startup*1	SrVCC	0.02	—	20	ms/V	
	During fast startup time*2		0.02	—	2		
	Voltage monitoring 1 reset enabled at startup *3, *4		0.02	—	—		

Note: When powering on AVCC0 and VCC, power them on at the same time or VCC first.
Note 1. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.
Note 2. When OFS1.(STUPLVD1REN, FASTSTUP) = 10b.
Note 3. When OFS1.STUPLVD1REN = 0.
Note 4. Turn on the power supply voltage according to the normal startup rising gradient because the register settings set by OFS1 are not read in boot mode.

Table 5.17 Output Values of Voltage (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for RIIC, ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7)		V_{OL}	—	0.6	V	I_{OL} = 3.0 mA
				—	0.4		I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7			—	0.4		I_{OL} = 0.4 mA
	RIIC pins	Standard mode		—	0.4		I_{OL} = 3.0 mA
		Fast mode		—	0.6		I_{OL} = 6.0 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7)*1		V_{OH}	VCC – 0.5	—	V	I_{OH} = –2.0 mA
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7			AVCC0 – 0.5	—		I_{OH} = –0.1 mA

Note 1. There are restrictions on AVCC0 and VCC depending on the usage conditions for the 12-bit D/A converter and I/O ports. When using ports PJ0 and PJ2 multiplexed with DA0 and DA1 as general I/O ports, make sure that VCC ≤ AVCC0.

Table 5.18 Output Values of Voltage (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 2.7 V, 1.8 V ≤ AVCC0 ≤ 2.7 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Low-level output voltage	All output ports (except for ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7)	V_{OL}	—	0.6	V	I_{OL} = 1.5 mA
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		—	0.4		I_{OL} = 0.4 mA
High-level output voltage	All output ports (except for ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7)*1	V_{OH}	VCC – 0.5	—	V	I_{OH} = –1.0 mA
	Ports P40 to P44, P46, ports P90 to P92, ports PJ6, PJ7		AVCC0 – 0.5	—		I_{OH} = –0.1 mA

Note 1. There are restrictions on AVCC0 and VCC depending on the usage conditions for the 12-bit D/A converter and I/O ports. When using ports PJ0 and PJ2 multiplexed with DA0 and DA1 as general I/O ports, make sure that VCC ≤ AVCC0.

Table 5.22 Clock Timing

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
XTAL external clock input cycle time		t_{Xcyc}	50	—	—	ns	Figure 5.18
XTAL external clock input high pulse width		t_{XH}	20	—	—	ns	
XTAL external clock input low pulse width		t_{XL}	20	—	—	ns	
XTAL external clock rising time		t_{Xr}	—	—	5	ns	
XTAL external clock falling time		t_{Xf}	—	—	5	ns	
XTAL external clock input wait time*1		t_{EXWT}	0.5	—	—	μs	
Main clock oscillator oscillation frequency	2.4 ≤ VCC ≤ 3.6	f_{MAIN}	1	—	20	MHz	
	1.8 ≤ VCC < 2.4		1	—	8		
Main clock oscillation stabilization time (crystal)*2		$t_{MAINOSC}$	—	3	—	ms	Figure 5.19
Main clock oscillation stabilization time (ceramic resonator)*2		$t_{MAINOSC}$	—	50	—	μs	
LOCO clock oscillation frequency		f_{LOCO}	3.44	4.0	4.56	MHz	
LOCO clock oscillation stabilization time		t_{LOCO}	—	—	0.5	μs	Figure 5.20
IWDT-dedicated clock oscillation frequency		f_{ILOCO}	12.75	15	17.25	kHz	
IWDT-dedicated clock oscillation stabilization time		t_{ILOCO}	—	—	50	μs	Figure 5.21
HOCO clock oscillation frequency		f_{HOCO}	31.52	32	32.48	MHz	T_a = –40 to 85°C
			31.68	32	32.32		T_a = –20 to 85°C
			31.36	32	32.64		T_a = –40 to 105°C
HOCO clock oscillation stabilization time		t_{HOCO}	—	—	56	μs	Figure 5.23
PLL input frequency*3		f_{PLLIN}	4	—	8	MHz	
PLL circuit oscillation frequency*3		f_{PLL}	32	—	48	MHz	
PLL clock oscillation stabilization time		t_{PLL}	—	—	50	μs	Figure 5.24
PLL free-running oscillation frequency		f_{PLLFR}	—	8	—	MHz	
USBPLL input frequency*5		f_{PLLIN}	—	6, 8*6	—	MHz	
USBPLL circuit oscillation frequency*5		f_{PLL}	—	48*6	—	MHz	
USBPLL clock oscillation stabilization time		t_{PLL}	—	—	50	μs	Figure 5.24
Sub-clock oscillator oscillation frequency*7		f_{SUB}	—	32.768	—	kHz	
Sub-clock oscillation stabilization time*4		t_{SUBOSC}	—	0.5	—	s	Figure 5.25

Note 1. Time until the clock can be used after the main clock oscillator stop bit (MOSCCR.MOSTP) is set to 0 (operating) when the external clock is stable.

Note 2. Reference values when an 8-MHz resonator is used.
When specifying the main clock oscillator stabilization time, set the MOSCWTCR register with a stabilization time value that is equal to or greater than the resonator-manufacturer-recommended value.
After changing the setting of the MOSCCR.MOSTP bit so that the main clock oscillator operates, read the OSCOVFSR.MOOVF flag to confirm that is has become 1, and then start using the main clock.

Note 3. The VCC range should be 2.4 to 3.6 V when the PLL is used.

Note 4. After changing the setting of the SOSCCR.SOSTP bit or RCR3.RTCEN bit so that the sub-clock oscillator operates, only start using the sub-clock after the sub-clock oscillation stabilization wait time that is equal to or greater than the oscillator-manufacturer-recommended value has elapsed.
Reference value when a 32.768-kHz resonator is used.

Note 5. The VCC range should be 3.0 to 3.6 V when the USBPLL is used.

Note 6. The input frequency can be set to 6 or 8 MHz only and the oscillation frequency can be set to 48 MHz only.

Note 7. Only 32.768 kHz can be used.

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.24 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.29
			Main clock oscillator and PLL circuit operating*3	t_{SBYPC}	—	2	3	ms	
		External clock input to main clock oscillator	Main clock oscillator operating*4	t_{SBYEX}	—	35	50	µs	
			Main clock oscillator and PLL circuit operating*5	t_{SBYPE}	—	70	95	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	µs	
		HOCO clock oscillator operating*6		t_{SBYHO}	—	40	55	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of PLL is 32 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 4. When the frequency of the external clock is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 5. When the frequency of PLL is 32 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 6. When the frequency of HOCO is 32 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

Table 5.25 Timing of Recovery from Low Power Consumption Modes (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Middle-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.29
			Main clock oscillator and PLL circuit operating*3	t_{SBYPC}	—	2	3	ms	
		External clock input to main clock oscillator	Main clock oscillator operating*4	t_{SBYEX}	—	3	4	µs	
			Main clock oscillator and PLL circuit operating*5	t_{SBYPE}	—	65	85	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	600	750	µs	
		HOCO clock oscillator operating*6		t_{SBYHO}	—	40	50	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	4.8	7	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.
Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.
Note 2. When the frequency of the crystal is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 3. When the frequency of PLL is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.
Note 4. When the frequency of the external clock is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.
Note 5. When the frequency of PLL is 12 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

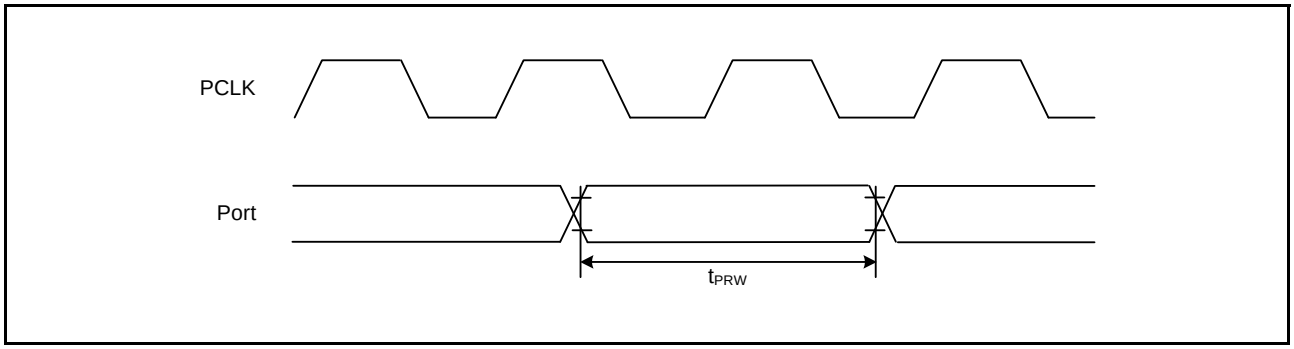


Figure 5.33 I/O Port Input Timing

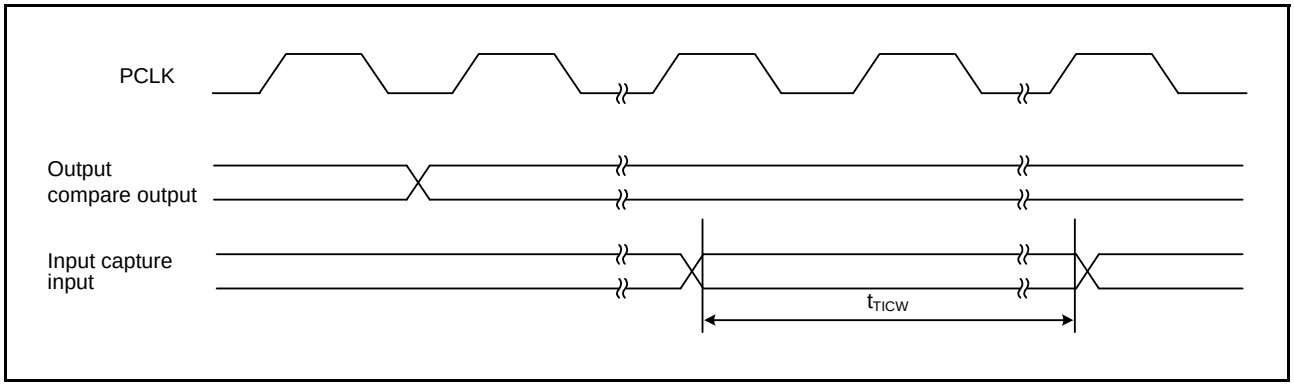


Figure 5.34 MTU2 Input/Output Timing

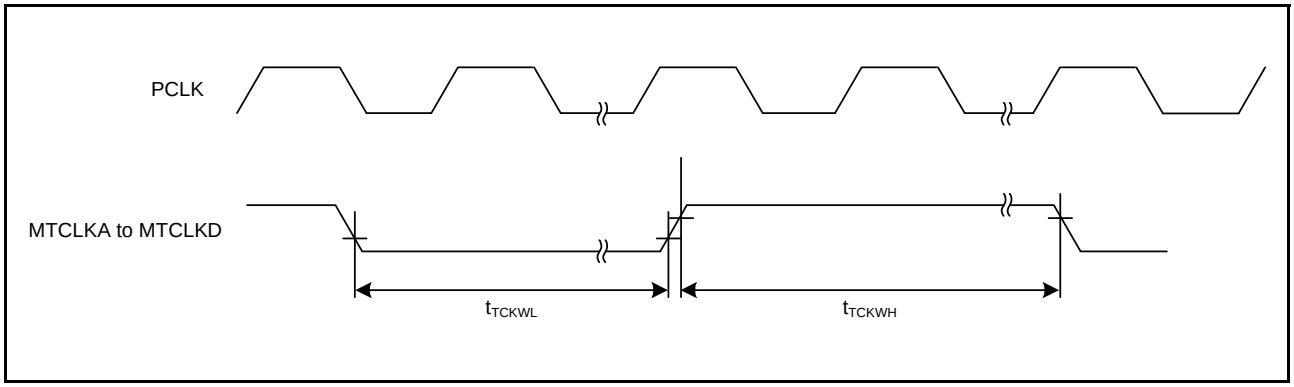


Figure 5.35 MTU2 Clock Input Timing

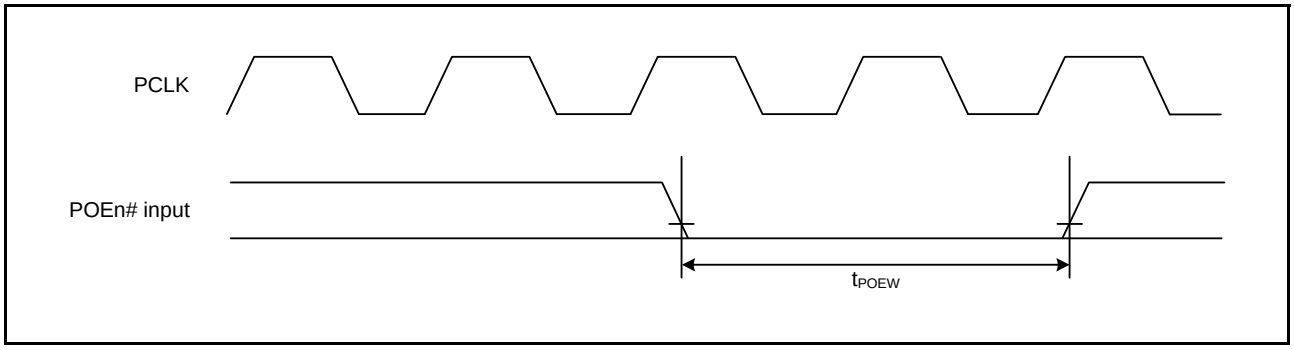


Figure 5.36 POE# Input Timing

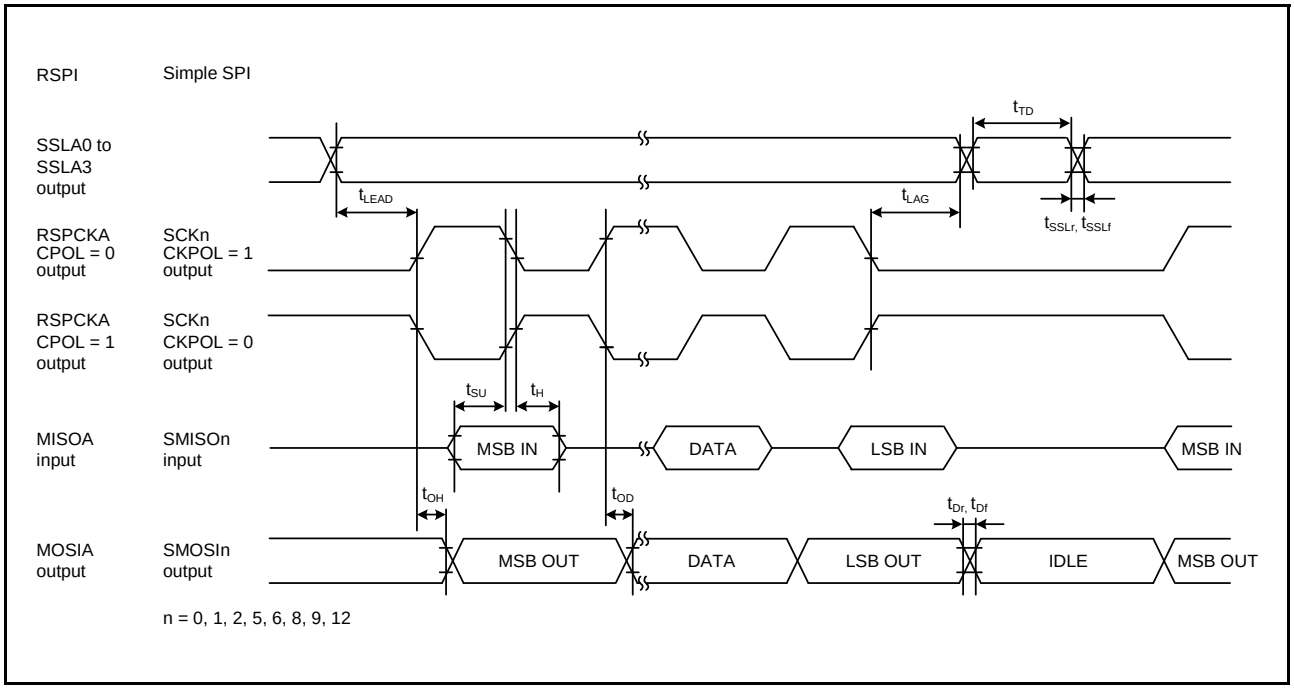


Figure 5.45 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Set to Division Ratio Other Than Divided by 2) and Simple SPI Timing (Master, CKPH = 0)

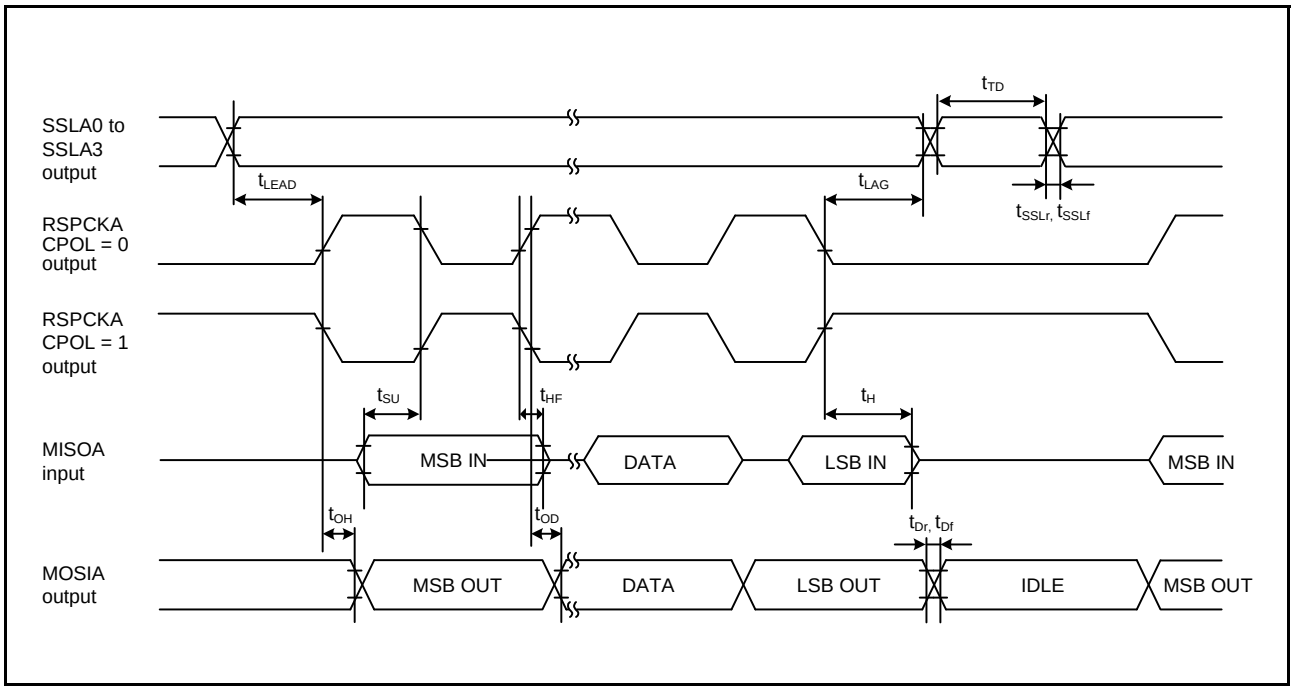


Figure 5.46 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Set to Divided by 2)

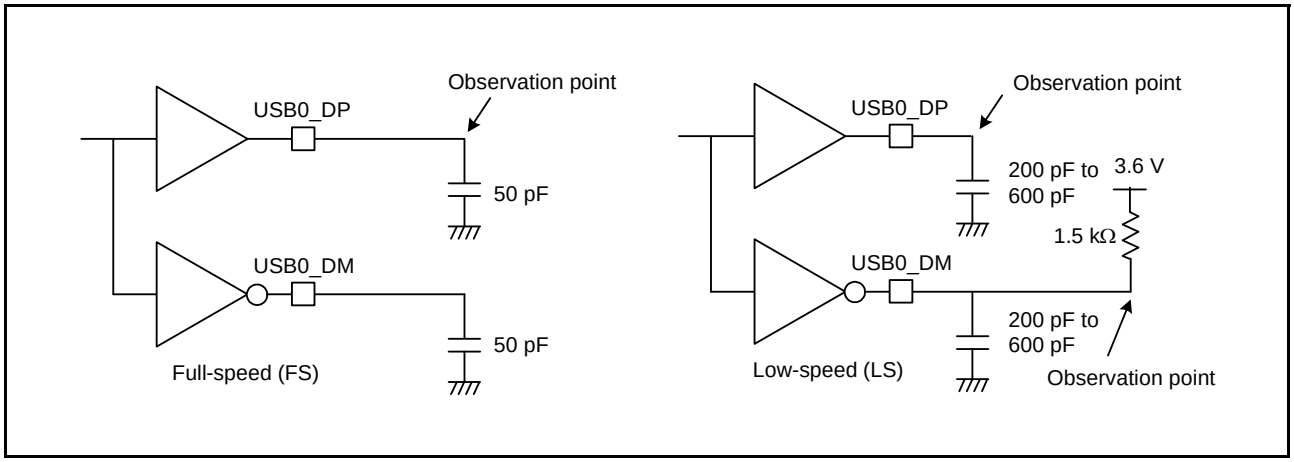


Figure 5.55 Test Circuit

Table 5.38 A/D Conversion Characteristics (2)

Conditions: 2.4 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.4 V ≤ AVCC0 ≤ 3.6 V, 2.4 V ≤ VREFH0 ≤ AVCC0,
VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		4	—	16	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance (Max.) = 1.0 kΩ	2.062 (0.625)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 09h
		2.750 (1.313)*2	—	—	µs	Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±6.0	LSB	
Full-scale error		—	±1.25	±6.0	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±3.0	±8.0	LSB	
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.5	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

Table 5.39 A/D Conversion Characteristics (3)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, 1.8 V ≤ VREFH0 ≤ AVCC0,
VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	8	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance (Max.) = 5.0 kΩ	4.875 (1.250)*2	—	—	µs	High-precision channel ADCSR.ADHSC bit = 0 ADSSTRn.SST[7:0] bits = 09h
		6.250 (2.625)*2	—	—	µs	Normal-precision channel ADCSR.ADHSC bit = 0 ADSSTRn.SST[7:0] bits = 14h
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±0.5	±24.0	LSB	
Full-scale error		—	±1.25	±24.0	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±2.75	±32.0	LSB	
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.25	±12.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

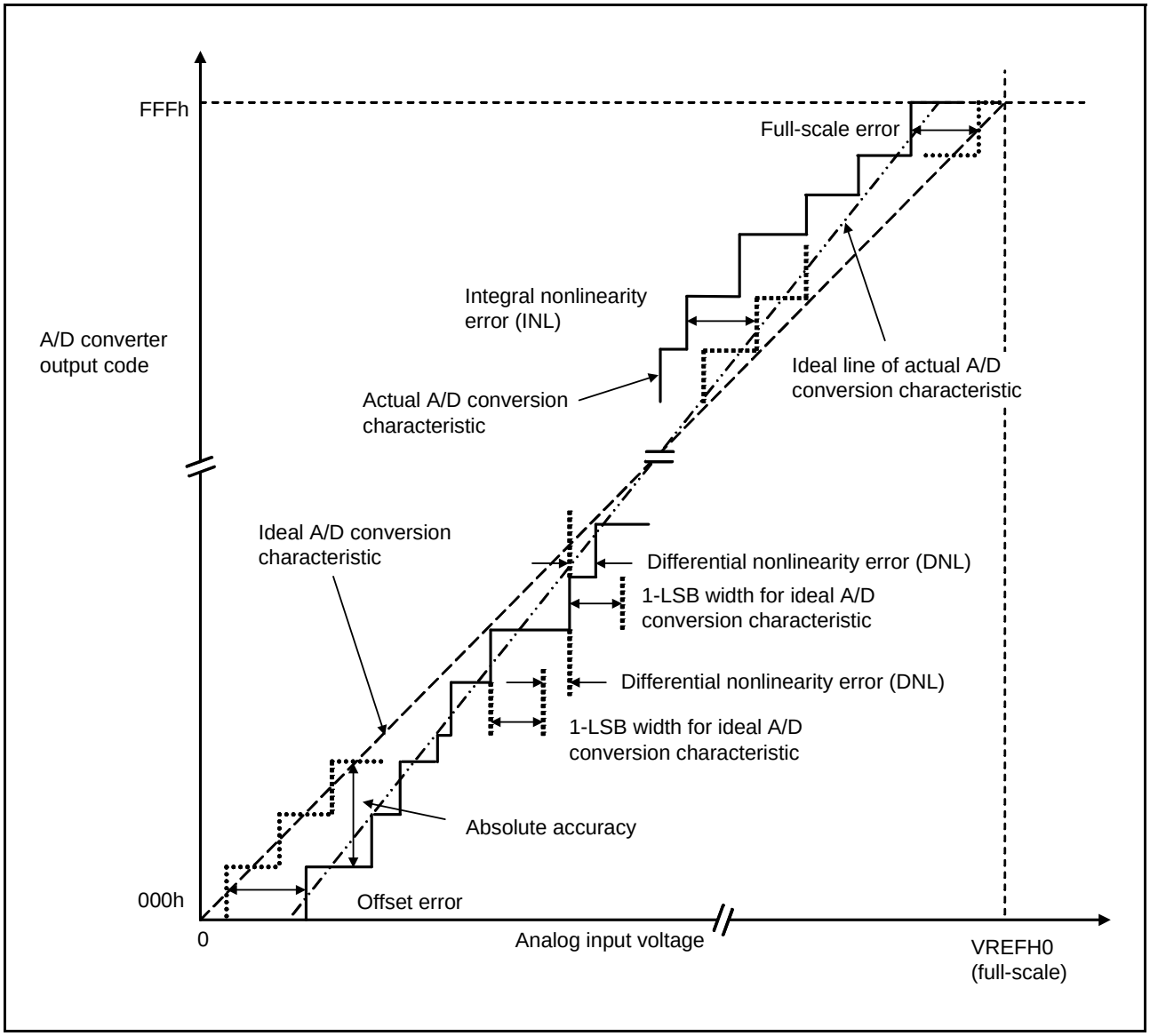


Figure 5.57 Illustration of A/D Converter Characteristic Terms

Absolute accuracy

Absolute accuracy is the difference between output code based on the theoretical A/D conversion characteristics, and the actual A/D conversion result. When measuring absolute accuracy, the voltage at the midpoint of the width of analog input voltage (1-LSB width), that can meet the expectation of outputting an equal code based on the theoretical A/D conversion characteristics, is used as an analog input voltage. For example, if 12-bit resolution is used and if reference voltage (VREFH0 = 3.072 V), then 1-LSB width becomes 0.75 mV, and 0 mV, 0.75 mV, 1.5 mV, ... are used as analog input voltages.

If analog input voltage is 6 mV, absolute accuracy = ±5 LSB means that the actual A/D conversion result is in the range of 003h to 00Dh though an output code, 008h, can be expected from the theoretical A/D conversion characteristics.

Integral nonlinearity error (INL)

Integral nonlinearity error is the maximum deviation between the ideal line when the measured offset and full-scale errors are zeroed, and the actual output code.

5.11 Power-On Reset Circuit and Voltage Detection Circuit Characteristics

Table 5.57 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	1.35	1.50	1.65	V	Figure 5.62, Figure 5.63
	Voltage detection circuit (LVD1)*1	V_{det1_4}	3.00	3.10	3.20	V	Figure 5.64 At falling edge VCC
		V_{det1_5}	2.91	3.00	3.09		
		V_{det1_6}	2.81	2.90	2.99		
		V_{det1_7}	2.70	2.79	2.88		
		V_{det1_8}	2.60	2.68	2.76		
		V_{det1_9}	2.50	2.58	2.66		
		V_{det1_A}	2.40	2.48	2.56		
		V_{det1_B}	1.99	2.06	2.13		
		V_{det1_C}	1.90	1.96	2.02		
		V_{det1_D}	1.80	1.86	1.92		

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD2), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet1_n denotes the value of the LVDLVLR.LVD1LVL[3:0] bits.

Table 5.58 Power-On Reset Circuit and Voltage Detection Circuit Characteristics (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Voltage detection circuit (LVD2)*1	V_{det2_0}	2.71	2.90	3.09	V	Figure 5.65 At falling edge VCC
		V_{det2_1}	2.43	2.60	2.77		
		V_{det2_2}	1.87	2.00	2.13		
		V_{det2_3}*2	1.69	1.80	1.91		
Wait time after power-on reset cancellation	At normal startup*3	t_{POR}	—	9.1	—	ms	Figure 5.63
	During fast startup time*4	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 1 reset cancellation	Power-on voltage monitoring 1 reset disabled*3	t_{LVD1}	—	568	—	µs	Figure 5.64
	Power-on voltage monitoring 1 reset enabled*4		—	100	—		
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.65
Response delay time		t_{det}	—	—	350	µs	Figure 5.62
Minimum VCC down time*5		t_{VOFF}	350	—	—	µs	Figure 5.62, VCC = 1.0 V or above
Power-on reset enable time		$t_{W\ (POR)}$	1	—	—	ms	Figure 5.63, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{\ (E-A)}$	—	—	300	µs	Figure 5.64, Figure 5.65
Hysteresis width (LVD1 and LVD2)		V_{LVH}	—	70	—	mV	Vdet1_4 selected
			—	60	—		Vdet1_5 to 9, LVD2 selected
			—	50	—		When selection is from among Vdet1_A to B.
			—	40	—		When selection is from among Vdet1_C to D.

Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

Note 1. n in the symbol Vdet2_n denotes the value of the LVDLVLR.LVD2LVL[3:0] bits.

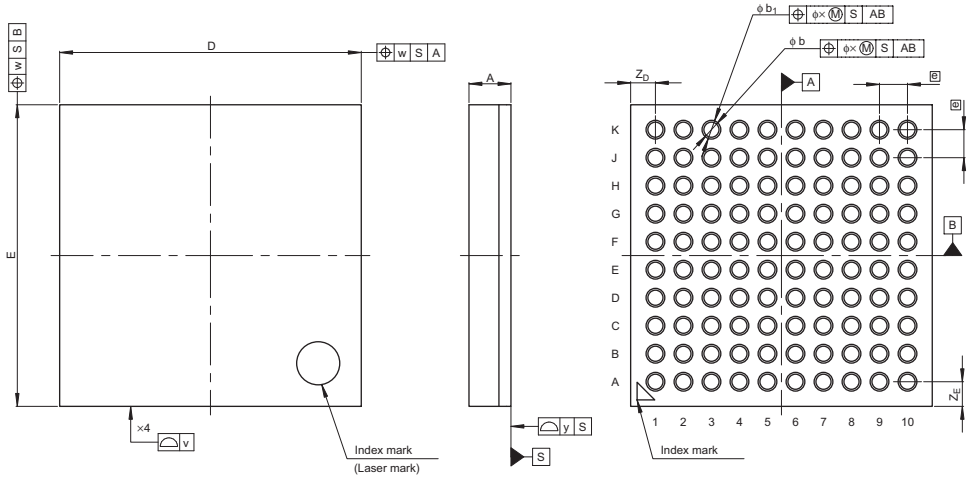
Note 2. Vdet2_3 selection can be used only when the CMPA2 pin input voltage is selected and cannot be used when the power supply voltage (VCC) is selected.

Note 3. When OFS1.(STUPLVD1REN, FASTSTUP) = 11b.

Note 4. When OFS1.(STUPLVD1REN, FASTSTUP) ≠ 11b.

Note 5. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA100-7x7-0.65	PTLG0100JA-A	100F0G	0.1g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	7.0	—
E	—	7.0	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.65	—
b	0.31	0.35	0.39
b_1	0.385	0.435	0.485
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.575	—

Figure B 100-Pin TFLGA (PTLG0100JA-A)

NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.